

Electronic Patent Application Fee Transmittal

Application Number:	10750059			
Filing Date:	30-Dec-2003			
Title of Invention:	Solder ball pad structure			
First Named Inventor:	Hiroshi Miyazaki			
Filer:	Yingsheng Tung/Jackie McBride			
Attorney Docket Number:	TI-36833			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 1 month with \$0 paid	1251	1	120	120

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				120